

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

Memorandum of License for Registration

CONVEYING PARTY DATA

Name	Execution Date
Surface Technology Systems plc	12/23/2005

RECEIVING PARTY DATA

Name:	Sumitomo Precision Products Co. Ltd.
Street Address:	1-10 Fusho-cho
City:	Amagasaki City, Hyogo
State/Country:	JAPAN
Postal Code:	660-0891

PROPERTY NUMBERS Total: 12

Property Type	Number
Patent Number:	6261962
Patent Number:	6051503
Patent Number:	6458239
Patent Number:	6602384
Patent Number:	6259209
Patent Number:	6534922
Patent Number:	6239404
Patent Number:	6628500
Patent Number:	6187685
Patent Number:	6602433
Application Number:	09462263
Application Number:	09601958

CORRESPONDENCE DATA

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500120421

PATENT
REEL: 017846 FRAME: 0567

OP \$480.00 6261962

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ATTORNEY DOCKET NUMBER:

SUMITOMO/PRIMAXX

NAME OF SUBMITTER:

Eileen Sullivan

Total Attachments: 6

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Memorandum of License for Registration

Date: May 25, 2006

Between

Surface Technology Systems plc (No. 1786418) whose registered office is at Imperial Park, Newport, Gwent, NP10 8UJ, in the United Kingdom (hereinafter referred to as "Licensor")

And

Sumitomo Precision Products Co. Ltd. a company incorporated in Japan, whose principal place of business is at 1-10 Fusho-cho, Amagasaki City, Hyogo, 660-0891, Japan (hereinafter referred to as "Licensee")

Recitals:

A. The Licensor is the registered proprietor in the United States of America of 6,261,962, patent number 6,051,503, patent number 6,458,239, patent number 6,602,384, patent number 6,259,209, patent number 6,534,922, patent number 6,239,404, patent number 6,628,500, patent number 6,187,685 and patent number 6,602,433 ("Patents"), and patent application number 09/462,263 and patent application number 09/601,958 ("Patent Applications").

B. By an agreement dated December 23, 2005 ("Principal Agreement") it was agreed between the parties that the Licensor would grant to the Licensee a license in Japan under the Patents, together with all patents granted pursuant to the Patent Applications, on the terms and for the consideration set out in the Principal Agreement.

Operative Provisions:

1. Pursuant to and for the consideration specified in the Principal Agreement, the Licensor grants to the Licensee a license to use the Patents and related Know-how in the Silicon Etching Field:

- (a) to manufacture at its factories in Japan Licensed Silicon Etching Products as listed in Schedule 1 and Spares for those Products;
- (b) to sell and distribute such manufactured Licensed Silicon Etching Products and Spares for those Products in Japan;
- (c) to provide support (including without limitation sale and supply of Spares) in respect of the Licensed Silicon Etching Products and Spares for those Products in Japan;

in accordance with the provisions of the Principal Agreement and to do all other things within the scope of the Patent(s) on the terms and conditions of the Principal Agreement.

2. The Exclusive License granted with respect to the Patents shall commence on the Effective Date and continue until the earlier of:

- (a) the later of:

- (i) 10 years following the Effective Date; and
 - (ii) the expiration of the last to expire of the Patents listed in Schedule 2 or, if they are Patent Applications, until there is no further possibility of any of such Patent Applications proceeding to grant; and
 - (b) termination of the Principal Agreement in accordance with its terms.
3. The License is granted pursuant to the terms of the Principal Agreement and not in substitution for any license or licenses granted under the Principal Agreement. Nothing contained in this agreement adds to, detracts from or changes in any way anything in the Principal Agreement, which remains in full force and effect in accordance with its terms.

Executed by the Parties on the date first set out above.

Schedule 1: Silicon Etching Products

Schedule 2: Silicon Etching Patents

SIGNED by a duly authorized
signatory for and on behalf of
**SURFACE TECHNOLOGY
SYSTEMS PLC**

) Name (block capitals)
) Signature
) Status
)

John Saunders
.....
[Signature]
.....
CEO
.....

SIGNED by a duly authorized
signatory for and on behalf of
**SUMITOMO PRECISION
PRODUCTS CO., LTD.**

) Name (block capitals)
) Signature
) Status
)

Susumu Kamada
.....
[Signature]
.....
President
.....

Licensed Silicon Etching Products

The following list of Licensed Silicon Etching Products are described by the product name and description by which they are known as at the Effective Date.

The list will be amended by the parties should any change of product name or description occur following the Effective Date in respect of any identical product to which the current list refers.

Multiplex-Lite platform incorporating any of the following process modules:

- ASE-SR
- ASE-HR
- ASE-HRM
- ASE-Pegasus

Multiplex platform incorporating any of the following process modules:

- ASE-SR
- ASE-HR
- ASE-HRM
- ASE-Pegasus

MACS platform incorporating any of the following process modules:

- ASE-SR
- ASE-HR
- ASE-HRM
- ASE-Pegasus

ASPECT cluster platform incorporating any combination of the following process modules:

- ASE-SR
- ASE-HR
- ASE-HRM
- ASE-Pegasus

Multiplex-Lite Pro platform incorporating any of the following process modules:

- ASE-SR
- ASE-HR
- ASE-HRM
- ASE-Pegasus

Multiplex Pro platform incorporating any of the following process modules:

- ASE-SR
- ASE-HR
- ASE-HRM
- ASE-Pegasus

MACS Pro platform incorporating any of the following process modules:

- ASE-SR
- ASE-HR
- ASE-HRM
- ASE-Pegasus

Pro Tool cluster platform incorporating any combination of the following process modules:

- ASE-SR
- ASE-HR
- ASE-HRM
- ASE-Pegasus

Schedule 2**Silicon Etching Patents**

US Patent Number	Subject
6,261,962	DLC passivation for a switched etching process
6,051,503	Parameter ramping
6,458,239	Embedded Langmuir probes for feedback control of multiple ICP antennae
6,602,384	Single shielded Langmuir probe to measure plasma characteristics
6,259,209	Multiple ICP antennae in various geometries to enable control of plasma uniformity
6,534,922	Single ICP antenna (AOE geometry) and multiple antennae in specific geometries
6,239,404	Balanced feed of RF power to an ICP antenna
6,628,500	Method and apparatus for de-chucking a substrate from an electrostatic clamp
6,187,685	Method and apparatus to allow controlled etching to an insulating layer or substrate
6,602,433	Local gas generation system and delivery system for treating a substrate

Silicon Etching Patent Applications

US Patent Application Number	Subject
09 / 462,263	Self-cleaning antenna
09 / 601,958	Control of etch rate uniformity by application of magnetic fields in various geometrical configurations